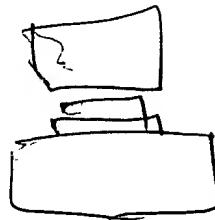


Claims Appendix:

15. A semiconductor component, comprising:

a solder containing at least two components with at least two metal-containing constituents including a first constituent X being formed of a precious metal and a second constituent Y being consumed during a soldering operation by one of reacting and being dissolved in materials which are to be joined, and said solder having a hypereutectic concentration of said second constituent Y;

a substrate; and



a semiconductor chip having a rear side and an adhesive or diffusion barrier provided on said rear side;

said semiconductor chip being secured at said rear side to said substrate by one of alloying and brazing using said solder to form a chip-substrate connection by said solder;

said solder containing a gold-tin compound (AuSn) having a composition by weight of Au to Sn of 70 to 30 and forming a layer having a thickness of from about 1 μm to about 2 μm .

Evidence Appendix:

No evidence pursuant to §§ 1.130, 1.131, or 1.132 or any other evidence has been entered by the Examiner and relied upon by appellant in the appeal.